## OCTAL 3-STATE INVERTING BUS TRANSCEIVER

High-Speed Silicon-Gate CMOS

The IN74ACT640 is identical in pinout to the LS/ALS640, HC/HCT640. The IN74ACT640 may be used as a level converter for interfacing TTL or NMOS outputs to High Speed CMOS inputs.

The IN74ACT640 is a 3-state transceiver that is used for 2-way asynchronous communication between data buses. The device has an active-low Output Enable pin, which is used to place the I/O ports into high-impedance states. The Direction control determines whether data flows from A to B or from B to A.

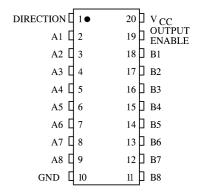
- TTL/NMOS Compatible Input Levels
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 to 5.5 V
- Low Input Current: 1.0 μA; 0.1 μA @ 25°C
- Outputs Source/Sink 24 mA

# N SUFFIX PLASTIC 20 1 DW SUFFIX SOIC

#### ORDERING INFORMATION

IN74ACT640N Plastic IN74ACT640DW SOIC T<sub>A</sub> = -40° to 85° C for all packages

#### **PIN ASSIGNMENT**

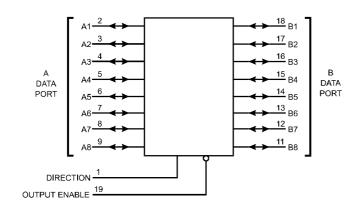


#### **FUNCTION TABLE**

Contr	ol Inputs	
Output	Direction	Operation
Enable		
L	L	Data Transmitted from Bus B to Bus A (inverted)
L	Н	Data Transmitted from Bus A to Bus B (inverted)
H	Х	Buses Isolated (High Impedance State)

X = don't care

#### **LOGIC DIAGRAM**



PIN 20=V<sub>CC</sub> PIN 10 = GND



#### IN74ACT640

#### **MAXIMUM RATINGS**\*

Symbol	Parameter	Value	Unit
$V_{CC}$	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
$V_{IN}$	DC Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
$V_{OUT}$	DC Output Voltage (Referenced to GND)	$-0.5$ to $V_{CC}$ +0.5	V
I <sub>IN</sub>	DC Input Current, per Pin	±20	mA
I <sub>OUT</sub>	DC Output Sink/Source Current, per Pin	±50	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA
$P_{D}$	Power Dissipation in Still Air, Plastic DIP+	750	mW
	SOIC Package+	500	
Tstg	Storage Temperature	-65 to +150	Ô
TL	Lead Temperature, 1 mm from Case for 10	260	°C
	Seconds		
	(Plastic DIP or SOIC Package)		

\*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

SOIC Package: : - 7 mW/°C from 65° to 125°C

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Max	Unit
$V_{CC}$	DC Supply Voltage (Referenced to GND)		5.5	V
$V_{IN}, V_{OUT}$	DC Input Voltage, Output Voltage (Referenced to GND)		V <sub>CC</sub>	V
$T_J$	Junction Temperature (PDIP)		140	°C
T <sub>A</sub>	Operating Temperature, All Package Types		+85	°C
I <sub>OH</sub>	Output Current - High		-24	mA
I <sub>OL</sub>	Output Current - Low		24	mA
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time * V <sub>CC</sub> =4.5 V	0	10	ns/V
	(except Schmitt Inputs) V <sub>CC</sub> =5.5 V	0	8.0	

V<sub>IN</sub> from 0.8 V to 2.0 V

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{IN}$  and  $V_{OUT}$  should be constrained to the range  $GND \le (V_{IN} \text{ or } V_{OUT}) \le V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{\text{CC}}$ ). Unused outputs must be left open.

<sup>+</sup>Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C

### **IN74ACT640**

DC ELECTRICAL CHARACTERISTICS(Voltages Referenced to GND)

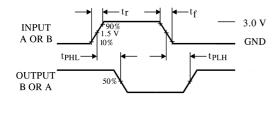
		, J	$V_{CC}$	Guaranteed Limits		
Symbol	Parameter	Test Conditions	>	25 °C	-40°C to 85°C	Unit
V <sub>IH</sub>	Minimum High- Level Input Voltage		4.5 5.5	2.0 2.0	2.0 2.0	V
$V_{IL}$	Maximum Low - Level Input Voltage	V <sub>OUT</sub> =0.1 V or V <sub>CC</sub> -0.1 V	4.5 5.5	0.8 0.8	0.8 0.8	V
$V_{OH}$	Minimum High- Level Output Voltage	I <sub>OUT</sub> ≤ -50 μA	4.5 5.5	4.4 5.4	4.4 5.4	V
		$^*V_{IN}$ = $V_{IH}$ or $V_{IL}$ $I_{OH}$ =-24 mA	4.5 5.5	3.86 4.86	3.76 4.76	
$V_{OL}$	Maximum Low- Level Output Voltage	I <sub>OUT</sub> ≤ 50 μA	4.5 5.5	0.1 0.1	0.1 0.1	V
		$^*V_{IN}$ = $V_{IH}$ or $V_{IL}$ $I_{OL}$ =24 mA $I_{OL}$ =24 mA	4.5 5.5	0.36 0.36	0.44 0.44	
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	5.5	±0.1	±1.0	μΑ
$\Delta I_{CCT}$	Additional Max. I <sub>CC</sub> /Input	V <sub>IN</sub> =V <sub>CC</sub> - 2.1 V	5.5		1.5	mA
l <sub>OZ</sub>	Maximum Three- State Leakage Current	$V_{IN}(OE) = V_{IH}$ or $V_{IL}$ $V_{IN} = V_{CC}$ or GND $V_{OUT} = V_{CC}$ or GND	5.5	±0.6	±6.0	μА
I <sub>OLD</sub>	+Minimum Dynamic Output Current	V <sub>OLD</sub> =1.65 V Max	5.5		75	mA
I <sub>OHD</sub>	+Minimum Dynamic Output Current	V <sub>OHD</sub> =3.85 V Min	5.5		-75	mA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>IN</sub> =V <sub>CC</sub> or GND	5.5	8.0	80	μА

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test. +Maximum test duration 2.0 ms, one output loaded at a time.

 $\underline{ \text{AC ELECTRICAL CHARACTERISTICS}}(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ C}_L = 50 \text{pF,Input } t_r = t_f = 3.0 \text{ ns})$ 

		Guara	nteed Limits	
Symbol	Parameter	25 °C	-40°C to	Unit
		,	85°C	
		Min Ma	x Min Max	
t <sub>PLH</sub>	Propagation Delay, A to B or B to A (Figure 1)	1.5   1.5	5   1.0   8.5	ns
t <sub>PHL</sub>	Propagation Delay, A to B or B to A (Figure 1)	1.5 8.0	1.0 9.0	ns
t <sub>PZH</sub>	Propagation Delay, Direction or Output Enable to A or B (Figure 2)	1.5 10.	0 1.0 11.0	ns
t <sub>PZL</sub>	Propagation Delay, Direction or Output Enable to A or B (Figure 2)	1.5 10.	0 1.0 11.0	ns
t <sub>PHZ</sub>	Propagation Delay, Direction or Output Enable to A or B (Figure 2)	1.5 10.	0 1.0 11.0	ns
t <sub>PLZ</sub>	Propagation Delay, Direction or Output Enable to A or B (Figure 2)	1.5 10.	0 1.0 11.0	ns
C <sub>IN</sub>	Maximum Input Capacitance	4.5	4.5	pF
Соит	Maximum Three-State I/O Capacitance (Output in High-Impedance State)	15	15	pF

		Typical @25°C,V <sub>CC</sub> =5.0 V		
$C_{PD}$	Power Dissipation Capacitance	45	pF	l



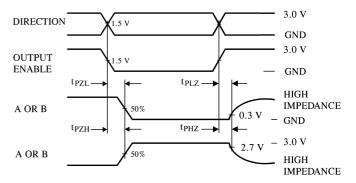


Figure 1. Switching Waveforms

Figure 2. Switching Waveforms

#### **EXPANDED LOGIC DIAGRAM**

